

## RX Family

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## USB Peripheral Human Interface Device Class Driver Using Firmware Integration Technology

### Introduction

This application note describes USB Peripheral Human Interface Devices Class Driver (PHID), which utilizes Firmware Integration Technology (FIT). This module performs hardware control of USB communication. It is referred to below as the USB-BASIC-F/W FIT module.

### Target Device

RX63N/RX631 Group  
RX65N/RX651 Group  
RX64M Group  
RX71M Group

When using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate MCU.

### Related Documents

1. Universal Serial Bus Revision 2.0 specification
2. RX63N/RX631 Group User's Manual: Hardware (Document number. R01UH0041EJ)
3. RX64M Group User's Manual: Hardware (Document number. R01UH0377EJ)
4. RX71M Group User's Manual: Hardware (Document number. R01UH0493EJ)
5. RX65N/RX651 Group User's Manual: Hardware (Document number. R01UH0590EJ)
6. RX65N/RX651-2M Group User's Manual: Hardware (Document number. R01UH0659EJ)
7. USB Basic Host and Peripheral Driver using Firmware Integration Technology Application Note (Document number. R01AN2025EJ)

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## 1. Overview

The USB PHID FIT module, when used in combination with the USB-BASIC-F/W FIT module, operates as a USB peripheral human interface device class driver (PHID). The PHID conforms to the USB Human Interface Device class specifications (referred to here as HID) and implements communication with a HID host.

This module supports the following functions.

- Data transfer to and from a USB host
- Response to HID class requests
- Response to function references from the HID host
- Interrupt OUT transfer

### 1.1 Please be sure to read

Please refer to the document (Document number: R01AN2025) for *USB Basic Host and Peripheral Driver using Firmware Integration Technology Application Note* when creating an application program using this driver.

This document is located in the "**reference\_documents**" folder within this package.

### 1.2 Note

This driver is not guaranteed to provide USB communication operation. The customer should verify operation when utilizing it in a system and confirm the ability to connect to a variety of different types of devices.

### 1.3 Terms and Abbreviations

Terms and abbreviations used in this document are listed below.

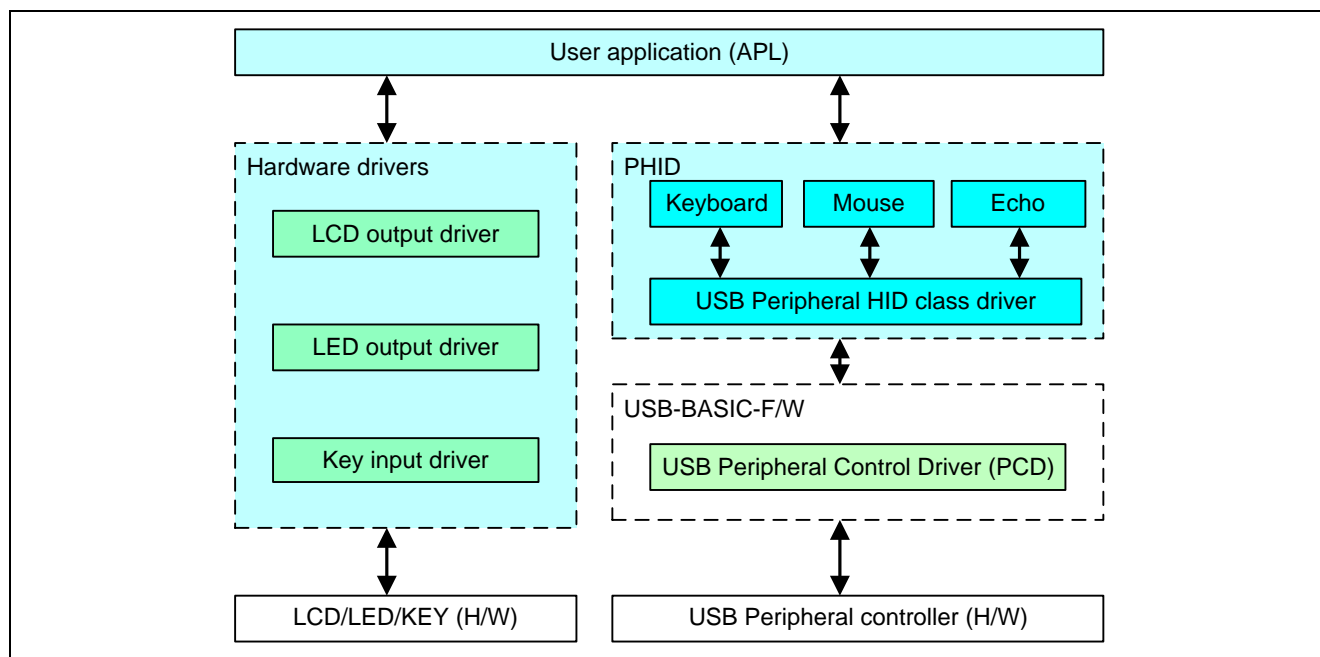
API	:	Application Program Interface
APL	:	Application program
HID	:	Human Interface Device class
PCD	:	Peripheral control driver of USB-BASIC-F/W
PDCD	:	Peripheral device class driver (device driver and USB class driver)
PHID	:	Peripheral Human Interface Devices
USB	:	Universal Serial Bus
USB-BASIC-FW	:	USB Host and Peripheral Basic Host and Peripheral Driver

### 1.4 USB PHID FIT Module

User needs to integrate this module to the project using `r_usb_basic`. User can control USB H/W by using this module API after integrating to the project.

## 2. Software Configuration

Figure 2-1 shows the configuration of the modules related to PHID



**Figure 2-1 Source Code Block Diagram**

**Table 2.1 Modules**

Module	Description
PHID	User switch operation on the RSK board is converted into HID reports. The transfer result is notified to APL by the callback function. In addition, communicate the output report of HID host to APL.
USB-BASIC-FW	USB Basic Host and Peripheral Driver ( Peripheral Hardware Control )

### 3. API Information

This Driver API follows the Renesas API naming standards.

#### 3.1 Hardware Requirements

This driver requires your MCU support the following features:

- USB

#### 3.2 Software Requirements

This driver is dependent upon the following packages:

- r\_bsp
- r\_usb\_basic

#### 3.3 Operating Confirmation Environment

Table 3-1 shows the operating confirmation environment of this driver.

Table 3-1 Operation Confirmation Environment

Item	Contents
Integrated Development Environment	Renesas Electronics e <sup>2</sup> studio V.6.0.0
C compiler	Renesas Electronics C/C++ compiler for RX Family V.2.07.00 Compile Option : -lang = c99
Endian	Little Endian, Big Endian
USB Driver Revision Number	Rev.1.22
Using Board	Renesas Starter Kit for RX63N Renesas Starter Kit for RX64M Renesas Starter Kit for RX71M Renesas Starter Kit for RX65N, Renesas Starter Kit for RX65N-2MB
Host Environment	The operation of this USB Driver module connected to the following OSes has been confirmed. 1. Windows® 7 2. Windows® 8.1 3. Windows® 10

### 3.4 Usage of Interrupt Vector

Table 3-2 shows the interrupt vector which this driver uses.

Table 3-2 List of Usage Interrupt Vectors

Device	Contents
RX63N RX631	USBIO Interrupt (Vector number: 35) / USBR0 Interrupt (Vector number: 90)
	USB D0FIFO0 Interrupt (Vector number: 33) / USB D1FIFO0 Interrupt (Vector number: 34)
	USB I1 Interrupt (Vector number: 38) / USBR1 Interrupt (Vector number: 91)
	USB D0FIFO1 Interrupt (Vector number: 36) / USB D1FIFO1 Interrupt (Vector number: 37)
RX64M RX71M	USBIO(GROUPB) Interrupt (Vector number: 189, Group interrupt source number : 62)
	USB D0FIFO0 Interrupt (Vector number: 34) / USB D1FIFO0 Interrupt (Vector number: 35)
	USBR0 Interrupt (Vector number: 90)
	USBAR Interrupt (Vector number: 94)
RX65N RX651	USB D0FIFO2 Interrupt (Vector number: 32) / USB D1FIFO2 Interrupt (Vector number: 33)
	USBIO(GROUPB) Interrupt (Vector number: 185, Group interrupt source number : 62)
	USB D0FIFO0 Interrupt (Vector number: 34) / USB D1FIFO0 Interrupt (Vector number: 35)
	USBR0 Interrupt (Vector number: 90)

### 3.5 Header Files

All API calls and their supporting interface definitions are located in `r_usb_basic_if.h` and `r_usb_phid_if.h`.

### 3.6 Integer Types

This project uses ANSI C99 "Exact width integer types" in order to make the code clearer and more portable. These types are defined in `stdint.h`.

### 3.7 Compile Setting

For compile settings, refer to chapter 6, **Configuration (r\_usb\_phid\_config.h)** in this document and chapter "Configuration" in the document (Document number: R01AN2025) for *USB Basic Host and Peripheral Driver using Firmware Integration Technology Application Note*.

### 3.8 ROM / RAM Size

The follows show ROM/RAM size of this driver.

1. RX64M, RX71M, RX65N/RX651

	Checks arguments	Does not check arguments
ROM size	18.8K bytes (Note 3)	18.4K bytes (Note 4)
RAM size	9K bytes	9K bytes

2. RX63N/RX631

	Checks arguments	Does not check arguments
ROM size	16.2K bytes (Note 3)	15.6K bytes (Note 4)
RAM size	8.6K bytes	8.6K bytes

[Note]

1. ROM/RAM size for BSP and USB Basic Driver is included in the above size.
2. The default option is specified in the compiler optimization option.

3. The ROM size of “Checks arguments” is the value when `USB_CFG_ENABLE` is specified to `USB_CFG_PARAM_CHECKING` definition in `r_usb_basic_config.h` file.
4. The ROM size of “Does not check arguments” is the value when `USB_CFG_DISABLE` is specified to `USB_CFG_PARAM_CHECKING` definition in `r_usb_basic_config.h` file.

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### 3.9 Argument

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For the structure used in the argument of API function, refer to chapter "**Structures**" in the document (Document number: R01AN2025) for *USB Basic Host and Peripheral Driver using Firmware Integration Technology Application Note*.

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### 3.10 Adding the FIT Module to Your Project

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This module must be added to each project in which it is used. Renesas recommends using “Smart Configurator” described at (1) or (3). However, “Smart Configurator” supports some RX devices. Please use the methods of (2) or (4) for unsupported RX devices.

- (1) Adding the FIT module to your project using “Smart Configurator” on e<sup>2</sup> studio

By using the “Smart Configurator” in e<sup>2</sup> studio, FIT module is automatically added to your project. Refer to “Renesas e<sup>2</sup> studio Smart Configurator User Guide (R20AN0451)”.

- (2) Adding the FIT module to your project using “FIT Configurator” on e<sup>2</sup> studio

By using the “FIT Configurator” in e<sup>2</sup> studio, FIT module is automatically added to your project. Refer to “Adding Firmware Integration Technology Modules to Projects (R01AN1723)”.

- (3) Adding the FIT module to your project using “Smart Configurator” on CS+

By using the “Smart Configurator Standalone version” on CS+, FIT module is automatically added to your project. Refer to “Renesas e<sup>2</sup> studio Smart Configurator User Guide (R20AN0451)”.

- (4) Adding the FIT module to your project on CS+

In CS+, please manually add FIT module to your project. Refer to “Adding Firmware Integration Technology Modules to CS+ Projects (R01AN1826)”

## 4. USB Peripheral Human Interface Devices Class Driver (PHID)

### 4.1 Class Requests (Host to Peripheral)

This driver notifies to the application program when receiving the following class request.

For the class request processing, refer to chapter "USB Class Requests" in the document (Document number: R01AN2025) for *USB Basic Host and Peripheral Driver using Firmware Integration Technology Application Note*.

**Table 4.1 HID class requests**

Request	Code	Description
Get_Report	0x01	Receives a report from the HID host
Set_Report	0x09	Sends a report to the HID host
Get_Idle	0x02	Receives a duration (time) from the HID host
Set_Idle	0x0A	Sends a duration (time) to the HID host
Get_Protocol	0x03	Reads a protocol from the HID host
Set_Protocol	0x0B	Sends a protocol to the HID host
Get_Descriptor Descriptor Type : Class Class Descriptor Type : Report	0x06 (Standard)	Transmits a report descriptor
Get_Descriptor Descriptor Type : Class Class Descriptor Type : HID	0x06 (Standard)	Transmits an HID descriptor



## 4.2 Class Request Data Format

### 1. GetReport

**Table 4-1 GetReport Format**

bmRequestType	bRequest	wValue	wIndex	wLength	Data
0xA1	GET_REPORT (0x01)	ReportType & ReportID	Interface	ReportLength	Report

### 2. SetReport

**Table 4-2 SetReport Format**

bmRequestType	bRequest	wValue	wIndex	wLength	Data
0x21	SET_REPORT (0x09)	ReportType & ReportID	Interface	ReportLength	Report

### 3. GetIdle

**Table 4-3 GetIdle Format**

bmRequestType	bRequest	wValue	wIndex	wLength	Data
0xA1	GET_IDLE (0x02)	0(Zero) & ReportID	Interface	1(one)	Idle rate

### 4. SetIdle

**Table 4-4 SetIdle Format**

bmRequestType	bRequest	wValue	wIndex	wLength	Data
0x21	SET_IDLE (0x0A)	Duration & ReportID	Interface	0(zero)	Not applicable

### 5. GetProtocol

**Table 4-5 GetProtocol Format**

bmRequestType	bRequest	wValue	wIndex	wLength	Data
0xA1	GET_PROTOCOL (0x03)	0(zero)	Interface	0(zero)	0 (Boot Protocol) / 1 (Report Protocol)

### 6. SetProtocol

**Table 4-6 SetProtocol Format**

bmRequestType	bRequest	wValue	wIndex	wLength	Data
0x21	SET_PROTOCOL (0x0B)	0 (Boot Protocol) / 1 (Report Protocol)	Interface	0(zero)	Not applicable

## 5. API Functions

For API used in the application program, refer to chapter "**API Functions**" in the document (Document number: R01AN2025) for *USB Basic Host and Peripheral Driver using Firmware Integration Technology Application Note*.

## 6. Configuration (r\_usb\_phid\_config.h)

Please set the following according to your system.

Note:

Be sure to set *r\_usb\_basic\_config.h* file as well. For *r\_usb\_basic\_config.h* file, refer to chapter "**Configuration**" in the document (Document number: R01AN2025) for *USB Basic Host and Peripheral Driver using Firmware Integration Technology Application Note*.

### 1. Setting pipe to be used

Set the pipe number (PIPE6 to PIPE9) to use for Interrupt IN/OUT transfer. Do not set the same pipe number for the definitions of `USB_CFG_PHID_INT_IN` and `USB_CFG_PHID_INT_OUT`.

<code>#define</code>	<code>USB_CFG_PHID_INT_IN</code>	Pipe number (USB_PIPE6 to USB_PIPE9)
<code>#define</code>	<code>USB_CFG_PHID_INT_OUT</code>	Pipe number (USB_PIPE6 to USB_PIPE9)

Note:

For a system that does not support the OUT transfer, set *USB\_NULL* as the definition of *USB\_CFG\_PHID\_INT\_OUT*.

## 7. Creating an Application

Refer to the chapter “**Creating an Application Program**” in the document (Document number: R01AN2025) for *USB Basic Host and Peripheral Driver using Firmware Integration Technology Application Note*.

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## Revision Record

Rev.	Date	Description	
		Page	Summary
1.11	Sep 30, 2015	—	First edition issued
1.20	Sep 30, 2016	—	<ol style="list-style-type: none"> <li>1. RX65N and RX651 are added in Target Device.</li> <li>2. Supporting USB Host and Peripheral Interface Driver application note(Document No.R01AN3293EJ)</li> </ol>
1.21	Mar 31, 2017	—	<ol style="list-style-type: none"> <li>1. When the return value of <i>R_USB_GetEvent</i> function is USB_STS_READ_COMPLETE or USB_STS_WRITE_COMPLETE, the USB driver has been changed so that USB_PHID is set for the member <i>type</i> of <i>usb_ctrl_t</i> structure.</li> <li>2. The chapter <i>API Functions</i> is moved to the document (Document number: R01AN2025) of <i>USB Basic Host and Peripheral Driver Firmware Integration Technology</i>.</li> </ol>
1.22	Sep 30, 2017	—	Supporting RX65N/RX651-2M

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The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

### 1. Handling of Unused Pins

Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

### 2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.  
In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

### 3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

### 4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

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#### **Renesas Electronics America Inc.**

2801 Scott Boulevard Santa Clara, CA 95050-2549, U.S.A.  
Tel: +1-408-588-6000, Fax: +1-408-588-6130

#### **Renesas Electronics Canada Limited**

9251 Yonge Street, Suite 8309 Richmond Hill, Ontario Canada L4C 9T3  
Tel: +1-905-237-2004

#### **Renesas Electronics Europe Limited**

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.  
Tel: +44-1628-585-100, Fax: +44-1628-585-900

#### **Renesas Electronics Europe GmbH**

Arcadiastrasse 10, 40472 Düsseldorf, Germany  
Tel: +49-211-6503-0, Fax: +49-211-6503-1327

#### **Renesas Electronics (China) Co., Ltd.**

Room 1709, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100191, P.R.China  
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

#### **Renesas Electronics (Shanghai) Co., Ltd.**

Unit 301, Tower A, Central Towers, 555 Langao Road, Putuo District, Shanghai, P. R. China 200333  
Tel: +86-21-2226-0888, Fax: +86-21-2226-0999

#### **Renesas Electronics Hong Kong Limited**

Unit 1601-1611, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong  
Tel: +852-2265-6688, Fax: +852-2886-9022

#### **Renesas Electronics Taiwan Co., Ltd.**

13F, No. 363, Fu Shing North Road, Taipei 10543, Taiwan  
Tel: +886-2-8175-9600, Fax: +886-2-8175-9670

#### **Renesas Electronics Singapore Pte. Ltd.**

80 Bendemeer Road, Unit #06-02 Hyflux Innovation Centre, Singapore 339949  
Tel: +65-6213-0200, Fax: +65-6213-0300

#### **Renesas Electronics Malaysia Sdn.Bhd.**

Unit 1207, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia  
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

#### **Renesas Electronics India Pvt. Ltd.**

No.777C, 100 Feet Road, HALII Stage, Indiranagar, Bangalore, India  
Tel: +91-80-67208700, Fax: +91-80-67208777

#### **Renesas Electronics Korea Co., Ltd.**

12F., 234 Teheran-ro, Gangnam-Gu, Seoul, 135-080, Korea  
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